

ABSTRACT

In a chemical mechanical wafer processing apparatus, a platen for supporting a polishing pad, a manifold for delivering a chemical to the platen, a workpiece substantially in contact with a polishing pad supported by the platen, a light transmission medium for transmitting and receiving light to and from the workpiece, one end of the medium being substantially flush with the top of the polishing pad, the other end of the transmission medium having a hollow portion for receiving a light transmitting and receiving probe, thereby providing a light transmitting and receiving probe in close proximity to the workpiece. The platen and manifold of the apparatus are substantially of non-metallic material and may be joined by spaced clamps and latches.